tinyML. Summit

Miniature dreams can come true...

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Brains into sensors with Al in the Edge

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STMicroelectronics

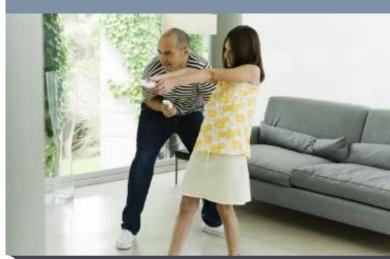
Is it a far-off future?



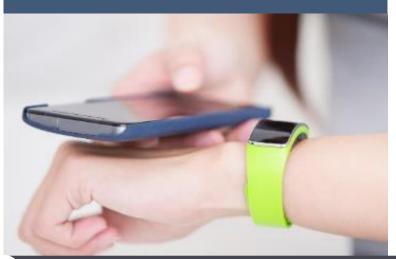


The MEMS journey

Offline era



Online era







2000

2010

A paradigm change in the man-machine interface

MEMS technology: from a concept to a product

Sensor's proliferation and connections to Cloud

Performance improvement and technology fusion

The fusion of technology and life

Standalone devices able to sense, process and take action



Systems where sensors live: the evolution

Offline era

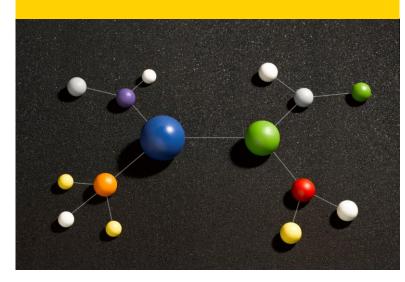
Fragmented



The simplest configuration: independent systems

Online era

Connected



Intertwined nodes enable efficient data exchange

Onlife era

Trained



Edge AI local decision making with maximum privacy



Industry 5.0 challenges











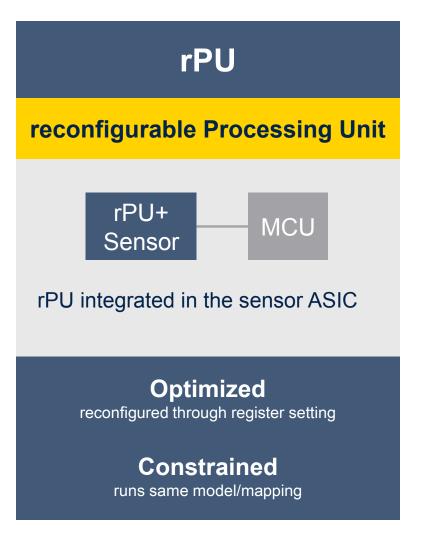
Sensor's semiconductors challenges for Edge Al

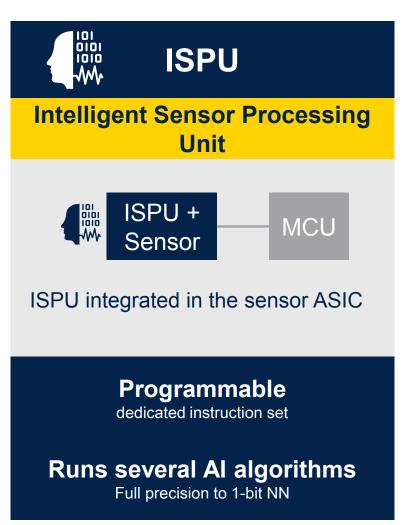
OPTIMAL POWER (uW) PER PERFORMANCE CAPABILITIES SUPER TINY SILICON LIMITED LOGIC AND MEMORY STORAGE **TECHNOLOGY ARCHITECTURE ECOSYSTEM COMPATIBILITY** ADVANCED TOOLS FOR INCREASED PRODUCTIVITY



Migrating intelligent processing From "on the Edge" to "in the Edge"

Sensor + MCU Microcontroller **MCU** Sensor MCU standalone or hosted in the sensor package **Standard** MCU runs the algorithms Runs any kind of SW provided it fits the MCU specs







ISPU: winning the challenges

DSP for real-time processing and Artificial Intelligence

Small area

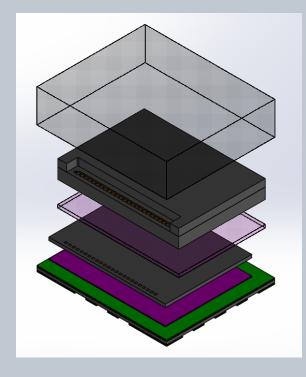
down to 8 kgates

Standard package

3 x 2.5 x 0.83 mm

RAM based

40 kiloBytes (program + execution)



Full precision

Floating Point Unit

Binary Neural Network

convolution acceleration

Optimization

Power consumption vs. performance



Optimization: power consumption vs performance

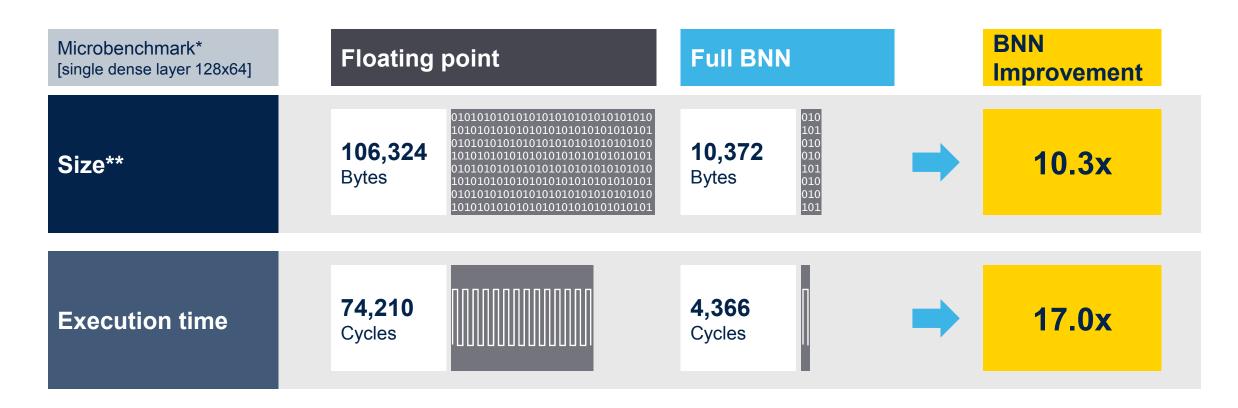
5x less current consumption for sensor fusion on ISPU than on M0 Below 600 μA for sensor fusion in the edge





Binary Neural Network (BNN) on ISPU

BNN on ISPU delivers over 10x better performance than floating point



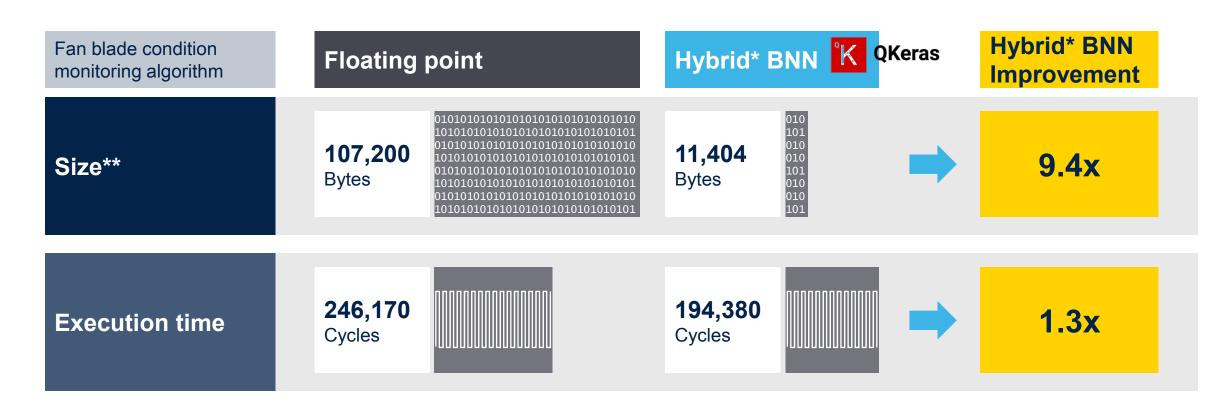
life gugmented

^{*} Kernel size = 128 and number of kernels = 64. ISPU set at 5MHz frequency

^{**} Full Application size: data + code + internal buffers + system libs

Hybrid Binary Neural Network (BNN) on ISPU

ISPU makes solutions ready for Onlife with faster and smaller algos



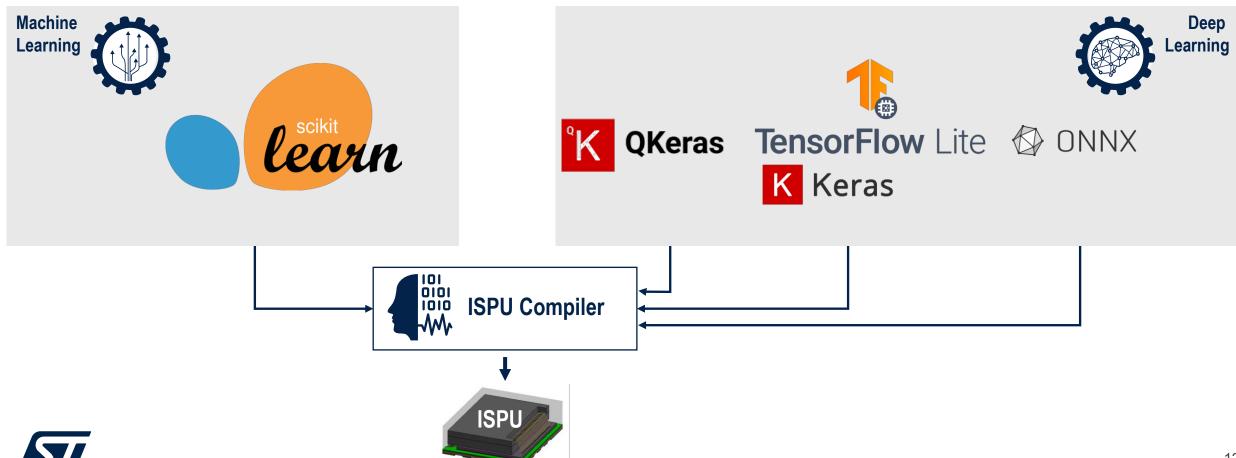


^{*} Some layers are floating point activations with binary weights, some are fully binarized (weights and activations). ISPU set at 5MHz frequency

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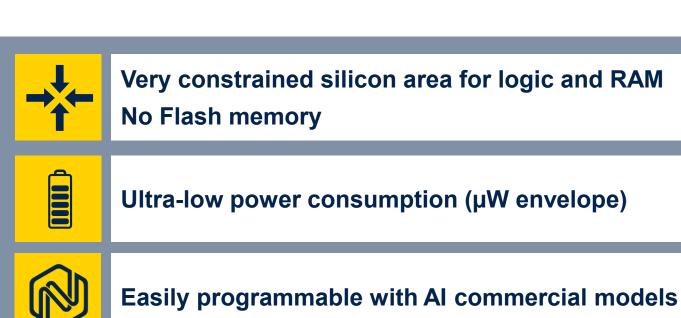
In-sensor Machine Learning & Deep Learning

ST ISPU delivers more options and greater freedom



ISPU in the Edge Al









Interoperates with







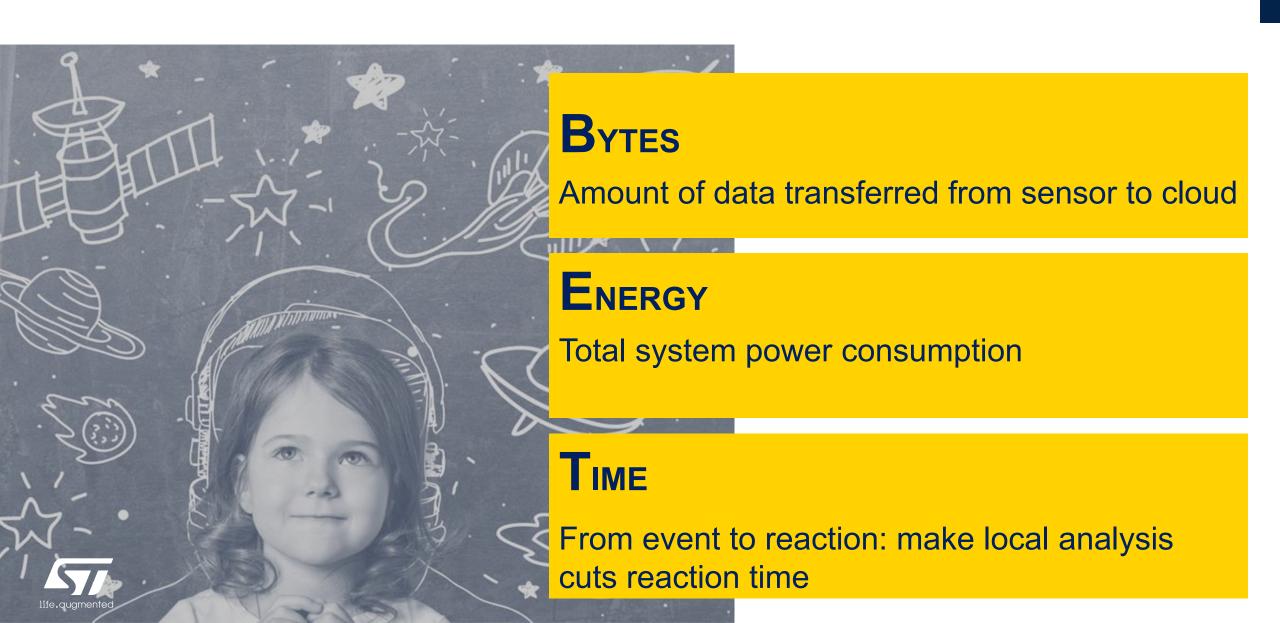




And?

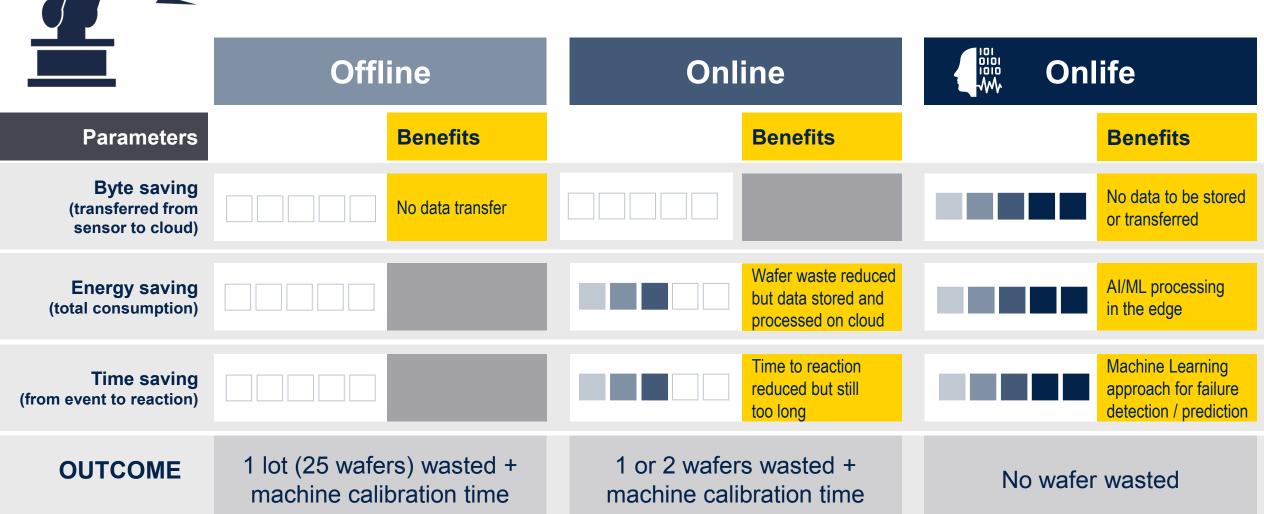


The B.E.T. benchmark





An example: the robotic arm handling





"In" the Edge: towards a new ecosystem

What's need to be explored together for ISPU?





Development of new benchmarks, and design tools to serve this innovation



Raise productivity and achieve synergies within the embedded developer community



Takeaways



Our technology starts with You



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Systems where sensors live

Offline era

Fragmented

Online era

Connected

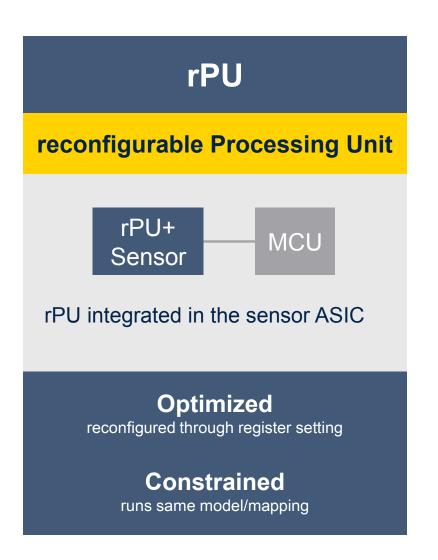
Onlife era

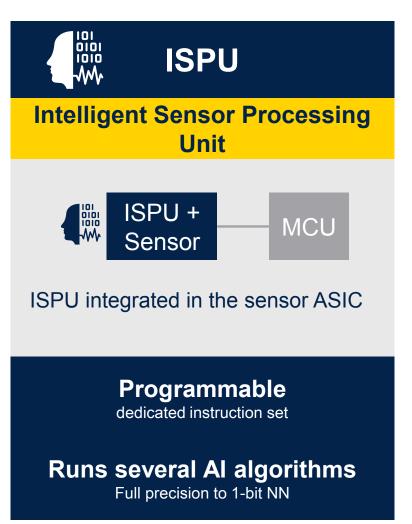
Trained



From "on the Edge" to "in the Edge"

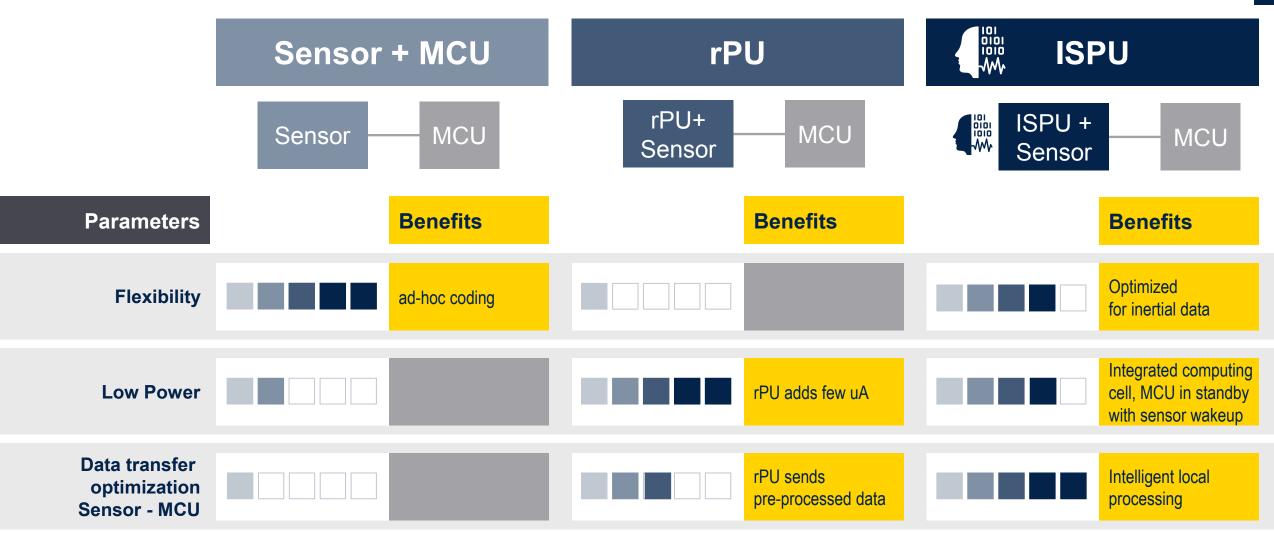
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One solution cannot fit all, but ISPU comes close





The 3 design criteria for working in the Edge



Local

In the Edge: data privacy, low power...



Fast

Ad-hoc processor customization for real-time execution



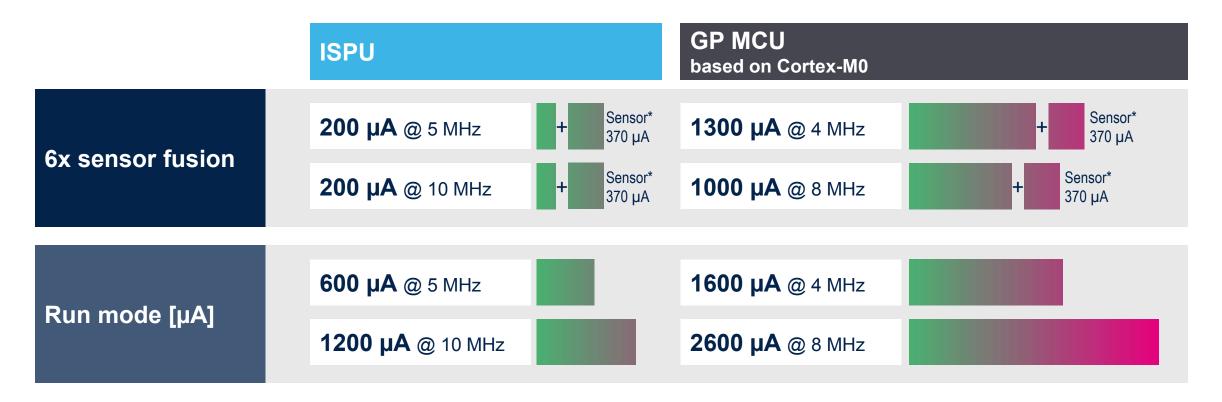
Intelligent

Runs complex AI analyses and takes actions



Sensor fusion on ISPU consumes far less current

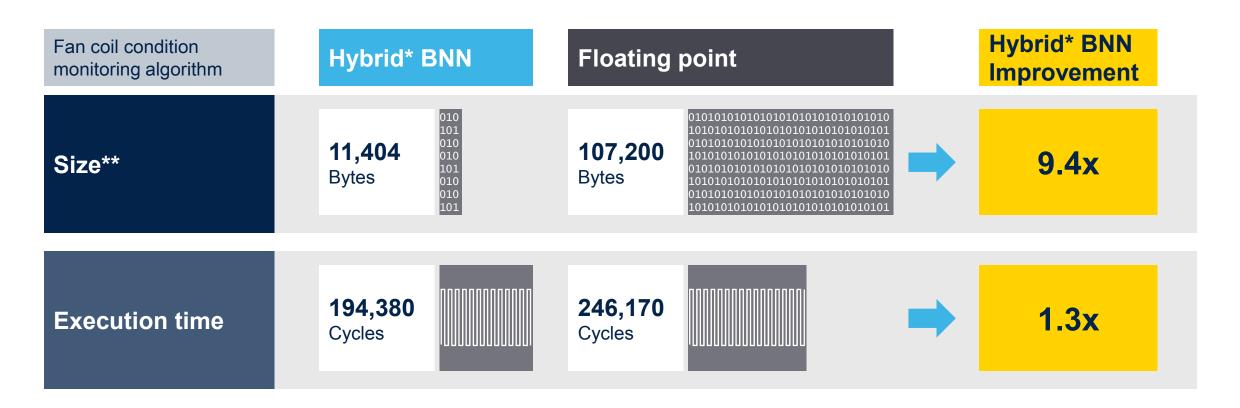
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Running Hybrid Binary Neural Network (BNN) for condition monitoring

ISPU makes solutions ready for Onlife with faster and smaller algos

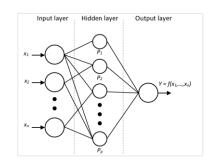


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BNN on ISPU far outperforms floating point

BNN on ISPU delivers over 10x better performance than floating point ISPU can now run dense SW layers in the Edge



Microbenchmark*
[single dense layer 128x64]

Full BNN

Floating point

BNN Improvement

Size**

10,372Bytes

106,324 Bytes

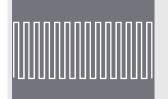


10.3x

Execution time

4,366 Cycles

74,210 Cycles





17.0x

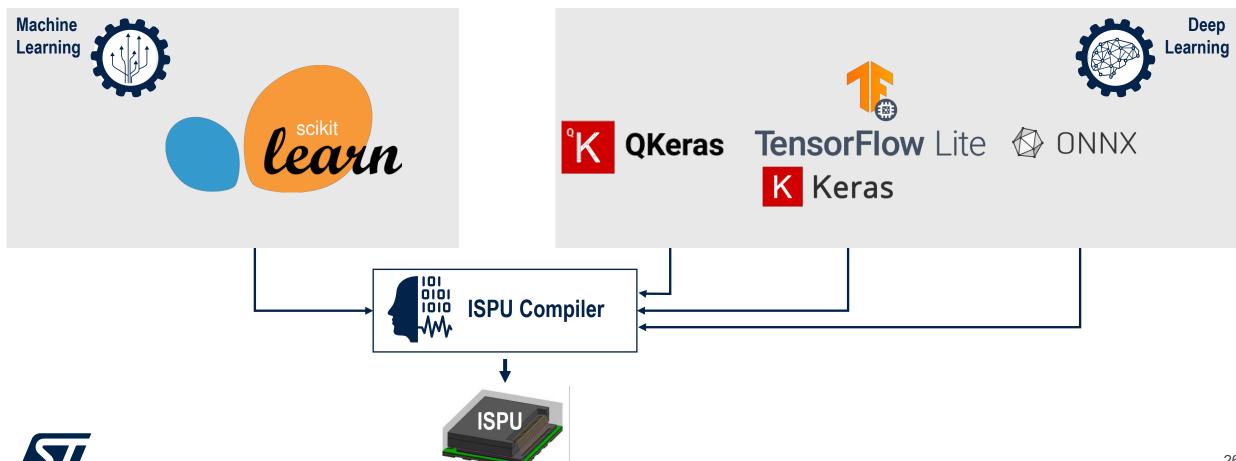


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ISPU - Toolkit



Compilation Tool

- Compiler (GNU) / Assembler (GNU) / Linker (GNU)
- Neural network library generation from high level tools (Keras, Tensorflow, etc.)
- Ad hoc optimization for ISPU target













IDE Tools

- Source-level debugger (GNU) / On-chip debugger
- Simulator (STMicroelectronics)
- Eclipse graphical interface





Runtime

- Platform SDK / Peripheral drivers
- Platform libraries





ISPU with NanoEdge™ AI for self-learning solutions





Onlife-ready: classify data patterns and detect in the edge



Commercial libraries ready to deploy on ISPU



Reference design with customization and support







Sensor's semiconductors challenges



ADVANCED TOOLS FOR INCREASED PRODUCTIVITY



ECOSYSTEM COMPATIBILITY WITH AI TOOLS



PROVEN TECHNOLOGY ARCHITECTURE IN SUPER TINY PACKAGE



LIMITED LOGIC AND MEMORY STORAGE FOR EDGE AI



OPTIMAL POWER (uW) PER PERFORMANCE CAPABILITIES



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